Government & Regulations

Ohio firm seeks $700M for two grand projects, aim to add 1,000-plus jobs

One project will establish a new facility adjacent to Wright-Patterson Air Force Base.

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An Ohio-based nonprofit dedicated to the acceleration of microelectronics technologies and the semiconductor revolution in the Midwest is seeking funds for two projects in the Dayton region: one for $250M and the second for $450M. The efforts would create thousands of new jobs and enhance national security.

The Midwest Microelectronics Consortium (MMEC) recently submitted two funding applications for grand projects within the region through the Dayton Regional Priority Development and Advocacy Committee (PDAC).

The MMEC was established in 2022, weeks before Intel Corp. broke ground on its $20 billion semiconductor site in central Ohio. The MMEC differs from other hubs, according to Ohio officials, with its role-based membership structure. Founding members include the University of Dayton, Sinclair Community College, Wright State University, the University of Cincinnati and Ohio State University.

In 2023, the Department of Defense designated the MMEC as a regional hub through the Microelectronics Commons program.

The Microelectronics Commons program designated eight hubs nationwide with $2 billion in funding from the 2022 CHIPS and Science Act, legislation intended to turbocharge a domestic chip-making industry. The hubs are designed to connect world-class academic institutions, corporate leaders and government partners with the aim of creating transformative technologies and turning them into real-word products focused on our DoD Warfighters.

The first project – titled the Silicon Heartland National Campus – will see the installation of a new facility adjacent to Wright-Patterson Air Force Base (WPAFB). The project will establish an end-to-end, base-adjacent collaborative national campus with direct transition paths to future warfighter platforms and commercialization opportunities across many market sectors.

The space will host a semiconductor clean room along with a fabrication and rapid prototyping facility, which will allow for the manufacturing of advanced material. Through these areas, the MMEC will be able to rapidly take a requirement from WPAFB and test its technology readiness level (TRL) and progress it onto a platform.

“The MMEC, through the CHIPS Act and OSD/DDR&E, is equipped, experienced, and highly motivated to significantly increase and improve the semiconductor lab to fab capacity and capability, enabling our next generation warfighter to deter and defeat our adversaries in any domain,” said Jackie Janning-Lask, CEO of MMEC. “Through the legislative process, this money will provide the investment (projects, infrastructure, and workforce development) to execute expeditiously on that objective. Our efforts are imperative to National Security and to the Dayton region.”

Jackie Janning-Lask, CEO of MMEC.
USAF

The project shares a similar name with Intel's grand project to construct two semiconductor fabrication plants in New Albany due to the MMEC having a close collaboration with Intel. The Dayton campus is just one location in the state that MMEC is developing, with the firm planning around $10 million worth of infrastructure at Ohio State.

"Dayton will be center of gravity for execution of these national security projects, from design to production, across MMEC's industry/academia/government partners," read the application submitted to PDAC.

The firm anticipates the direct creation of over 1,000 new jobs due to the project.

MMEC is applying to fund $250 million of the project through PDAC. Funds will be used for equipment purchases.

Another application was submitted to PDAC from MMEC for a project titled The Commons Cross Hub Capabilities Programmatic Funding Increase. The firm seeks to attract additional money to execute on projects that are being executed currently across six tech domains through an in-place rapid execution program.

Use of other under-utilized CHIPS Act monies will maximize current funding, while minimizing capability redundancies due to early effective standup of the Commons program.

MECommons is already executing end-to-end capabilities from design to rapid prototyping and production direct to weapon system platforms and commercial markets, including projects across electronic warfare, 5G/6G, commercial leap ahead, quantum, artificial intelligence and edge computing.

Through funding certain “selected” but unfunded critical projects across the Commons program – along with the first-ever digital, physical and workforce joint capability in partnership with WPAFB and Commons program partners and stakeholders – the execution of work will occur across all U.S. Commons Hubs, including MMEC and the Miami Valley.

MMEC is applying to fund $450 million of the project through PDAC. Funds will be used for equipment purchases.

THE LIST

Dayton-Area U.S. Department of Defense Contractors

2023 prime awards

Rank	Prior Rank	Organization
1	1	Peerless Technologies Corp.
2	2	Messer Construction Co.
3	3	Applied Research Solutions

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